QX250i[™] 2D AOI

High Value, Flexible Inspection for all Applications





BEST PERFORMANCE FOR BEST VALUE

- Top and Bottom High Resolution (12um) SIM with enhanced illumination enabling 50% productivity improvement.
- Production Ready in <13 minutes[†] with Al2
- 01005 Inspection Capability
- Easy Wedge-in Replacement of Existing Conveyor
- Lowest False Call Rate and Zero Escapes

[†]For pre-defined parts

^{*3} Year Warranty on standard parts only (excludes conveyor belts and other consumables); 1 year warranty on service

INTELLIGENT SENSING TECHNOLOGY

The SIM (Strobed Inspection Module) is the core engine behind every QX250i[™] /QX200i[™] system enabling 'on-the-fly' high performance inspection. Designed and manufactured exclusively by CyberOptics, the SIM is absolutely calibration-free and illuminates only when needed − reducing cost of ownership and power consumption.

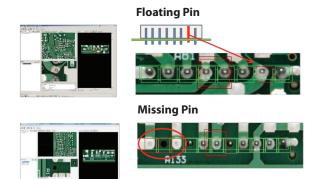
The dual top and bottom SIMs provide a single platform for the inspection and defect review process that shortens the production line and drives ~50% productivity improvement.

The SIM on the QX250i[™] is designed with enhanced illumination – delivering the best 01005 and solder joint inspection performance ever. With an 80 Megapixel sensor and higher resolution (12 µm), you get crisp, perfect quality images for more accurate defect review. (The QX200i[™] uses an 40 Megapixel sensor and to acheive a resolution of 17 µm.)

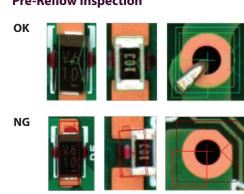


SIM (Strobe Inspection Module)

Selective Soldering Inspection



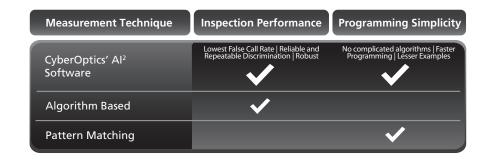
Pre-Reflow Inspection

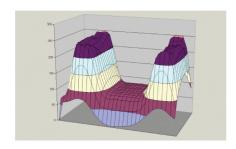


INSPECT 'ANYTHING'

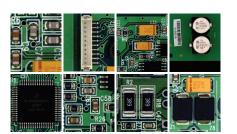
CyberOptics' Al² (Autonomous Image Interpretation) technology is a complete refactor of our proven Statistical Appearance Modeling techniques. Al² is all about keeping it simple - no parameters to adjust or algorithms to tune. And, you don't need to anticipate defects or pre-define variance either – Al² does it all for you.

Just draw a box, show a few good examples and you are ready to inspect just about anything. Add more images to the model and watch false call rates get even lower.





Al² Software: Unique Image Processing Technique



Components Inspected/ Detected

Al² – FASTER, SIMPLER AND SMARTER

With Al² technology, programming gets even faster – with a 90% reduction in examples required – so you get superior defect detection and low false call rates even with just **one example**. This means significantly lower tuning time and quality results with one panel inspection. Perfect for those high-mix or low volume applications!

With its unique ability to 'ignore' bad examples in a model, Al² offers precise discrimination even with excessive variance and minimizes effects of outlier examples.

Plus, it is a lot simpler with full support for unsupervised and semi-automatic model training. And, examples are pre-sorted so you can select and clear the ones you don't need – very quickly.

The pixel marking feature highlights defective spots, so you can identify genuine defects instantly.

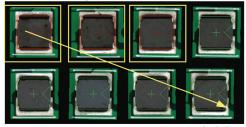
3-EASY-STEPS PROGRAMMING

Our latest software improvements take programming to a whole, new level – zero to production ready in **less than**13 minutes! All this is made possible, with an all-new data-rich, pre-loaded library and automated scripts that collect examples and update models – all on their own.

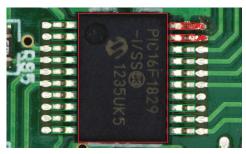
FAST, SCALABLE SPC SOLUTION

CyberReport[™] offers full-fledged machine-level to factory-level SPC capability with powerful historical analysis and reporting tools delivering complete traceability for process verification and yield improvement. CyberReport[™] is easy to setup and simple to use while providing fast charting with a compact database size.

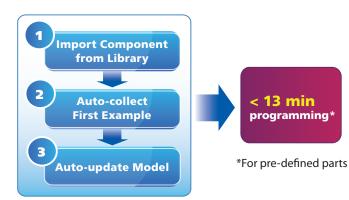
Worst Probability



Best Proba
Intelligent ranking of examples



Active Pixel Marking



Simplified Programming Process



Inspection Capabilities	QX250i	QX200i
Typical Scanning Speed	110 cm²/sec	150 cm ² /sec
Minimum Component Size	0402 mm (01005 in.)	
Board Length	Min. 50 mm (2 in.)/ Max. 405 mm (16 in.)	
Board Width	Min. 50 mm (2 in.)/ Max. 308 mm (12 in.)	
Component Height Clearance (max)	35 mm	30 mm
Board Edge Clearance (min)	3.0 mm (0.125 in.) – bottom side only	
Maximum Board Weight	3kg	
Maximum Board Warp	Up to +/-7 mm	
Component Types Inspected	Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others	
Solder Joint Defects Categories	Solder bridge, opens, lifted leads, wettability, excess and in sufficient solder, debris, and others	
Other Items Detected	Gold-finger contamination, pin-in-hole, bent pins, debris, and many others	
Component Position Categories	Component X, Y position and Rotation	
Vision System		
Imagers	80 Megapixel Sensor on each SIM module	40 Megapixel Sensor on each SIM module
Image Transfer Protocol	PCle	
Lighting	Strobe White Light (with dark/bright field)	
Resolution	12 μm pixel size	17 μm pixel size
Image Processing	Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (Al²) Technology	
Programming	Simple inline or offline	
CAD Import	Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)	
System Specifications		
Conveyor Height	Adjustable to 835 – 990 mm (33 – 39 in.)	
Machine Interface	SMEMA, RS232 and Ethernet	
Power Requirements	100-120V, 15 Amp max or 220-240V 10 Amp max, 50/69 Hz	
System Dimensions	100 x 104.7 x 124 cm	
Weight	249 kgs (548.951 lbs.)	
Machine Installation	<1 hour	
Options		

SPC Software, Offline Defect Rework Station, Sensor Alignment Target, Barcode Readers (1D/2D)

153cm (60.21n) (100cm (39.4in)

86.5cm (12.in) (41.2in)

Specifications subject to change without notice.